

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
-20V	$16m\Omega @ V_{GS} = -4.5V$	-9.0A
-200	$22m\Omega @ V_{GS} = -2.5V$	-7.7A

Features and Benefits

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Low On-Resistance
- ESD protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This MOSFET is designed to minimize on-state resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- **Battery Management Application**
- **Power Management Functions**
- **DC-DC Converters**

Mechanical Data

Case: U-DFN2020-6

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Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0

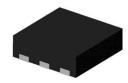
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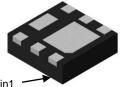
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.007 grams (Approximate)



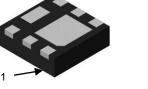




Top View



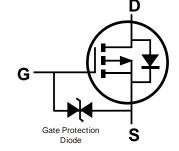
Bottom View





Bottom View

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Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2021UFDF-7	U-DFN2020-6	3,000/Tape & Reel
DMP2021UFDF-13	U-DFN2020-6	10.000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

U-DFN2020-6



P1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: C = 2015)M = Month (ex: 9 = September)

Date Code Key

Year	2014	4	2015		2016	20	17	2018		2019	2	2020
Code	В		С		D	1		F		G		Н
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	-20	V		
Gate-Source Voltage	V _{GSS}	±8	V		
Continuous Drain Current (Note C) V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ΙD	-9.0 -7.2	А
Continuous Drain Current (Note 6) V _{GS} = -4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-11.1 -8.9	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I_{DM}	-60	Α		
Continuous Source-Drain Diode Current (Note 6)	Is	-2.4	Α		
Avalanche Current (Note 7) L = 0.1mH	I _{AS}	-27	Α		
Avalanche Energy (Note 7) L = 0.1mH	E _{AS}	38	mJ		

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Total Power Dissination (Note 5)	$T_A = +25^{\circ}C$	Б	0.73	W	
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	P_{D}	0.47		
Thermal Peciatones, Junction to Ambient (Note 5)	Steady State	<u> </u>	172	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	121		
Total Power Dissipation (Note 6)	$T_A = +25$ °C	Pn	2.02	W	
Total Fower Dissipation (Note o)	$T_A = +70^{\circ}C$	FD	1.30		
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	<u> </u>	63		
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	42	°C/W	
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	18			
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 8)								
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$		
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	l	_	-1	μΑ	$V_{DS} = -20V, V_{GS} = 0V$		
Gate-Source Leakage	I _{GSS}	l	_	±10	μA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$		
ON CHARACTERISTICS (Note 8)								
Gate Threshold Voltage	V _{GS(th)}	-0.35	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$		
			12	16		$V_{GS} = -4.5V$, $I_{D} = -7.0A$		
Static Drain-Source On-Resistance	Dec (cu)		15	22	mΩ	$V_{GS} = -2.5V, I_D = -5.0A$		
Static Dialif-Source Off-Resistance	R _{DS} (ON)	_	19	40	11122	$V_{GS} = -1.8V, I_D = -3.0A$		
			21	80		$V_{GS} = -1.5V, I_D = -1.0A$		
Diode Forward Voltage	V_{SD}	l	-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -1.0A$		
DYNAMIC CHARACTERISTICS (Note 9)								
Input Capacitance	C _{iss}	_	2760	_		$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz		
Output Capacitance	Coss		262	_	pF			
Reverse Transfer Capacitance	C _{rss}	l	220	_		1 = 1:01/11/12		
Gate Resistance	Rg	_	16	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$		
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	34	_				
Total Gate Charge (V _{GS} = -8V)	Qg	_	59	_	nC	$V_{DS} = -15V, I_D = -4.0A$		
Gate-Source Charge	Qgs	_	3.5	_	lic			
Gate-Drain Charge	Q_{gd}	_	8.3	_				
Turn-On Delay Time	t _{D(on)}		7.5	_				
Turn-On Rise Time	t _r	_	25	_		$V_{DS} = -15V$, $V_{GS} = -4.5V$,		
Turn-Off Delay Time	t _{D(off)}	_	125	_	ns	$R_G = 1\Omega, I_D = -4.0A$		
Turn-Off Fall Time	t _f		96	_				
Reverse Recovery Time	t _{rr}	_	48	_	ns	I _F = -1.0A, di/dt = 100A/μs		
Reverse Recovery Charge	Qrr	_	33	_	nC	I _F = -1.0A, di/dt = 100A/µs		

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

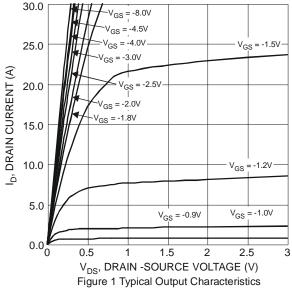
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

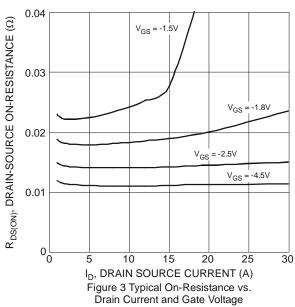
7. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.

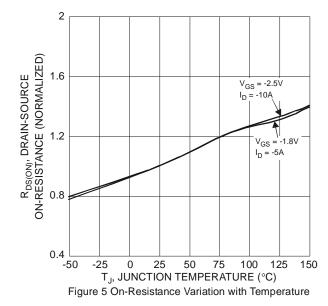
8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.

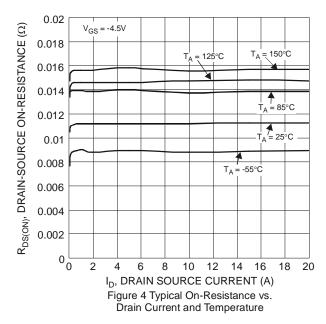








20 V_{DS} = -5.0V 18 16 ID, DRAIN CURRENT (A) 14 12 10 8 6 4 $T_A =$ 2 0 0 1.5 2.5 V_{GS} , GATE-SOURCE VOLTAGE (V) Figure 2 Typical Transfer Characteristics



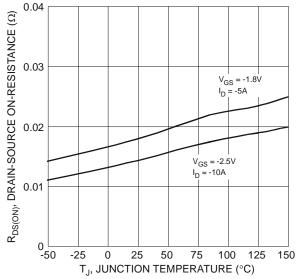


Figure 6 On-Resistance Variation with Temperature



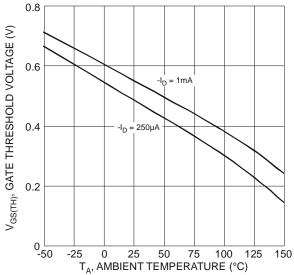
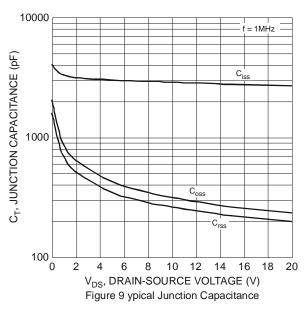
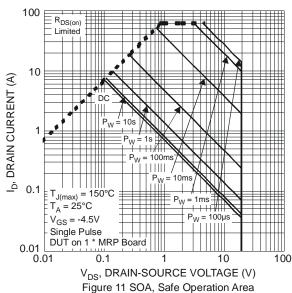
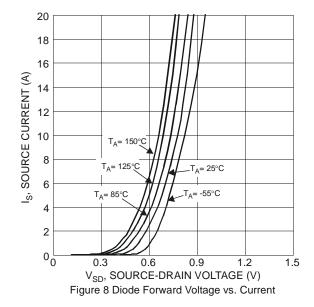
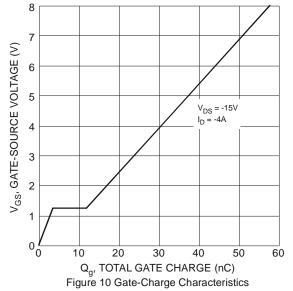


Figure 7 Gate Threshold Variation vs. Ambient Temperature

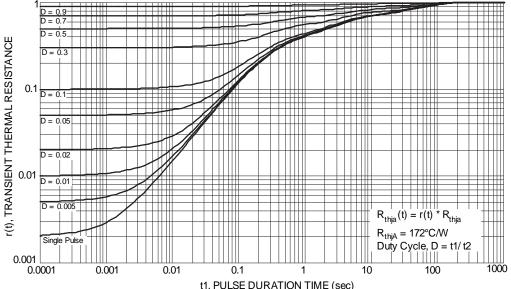








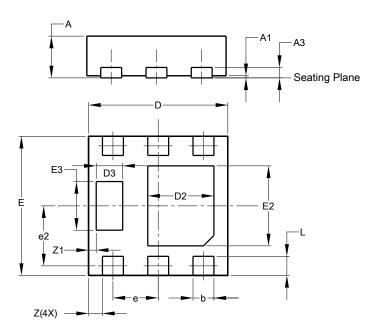






Package Outline Dimensions

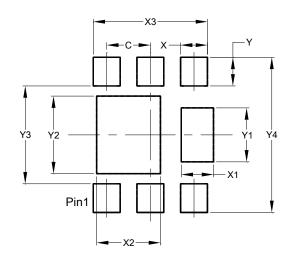
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



U-DFN2020-6								
(Type F)								
Dim	Min	Min Max Typ						
Α	0.57	0.63	0.60					
A1	0	0.05	0.03					
A3	-	-	0.15					
b	0.25	0.35	0.30					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
D3	0.33	0.43	0.38					
е	0.65 BSC							
e2	().863 B	SC					
Е	1.95	2.05	2.00					
E2	1.05	1.25	1.15					
E3	0.65	0.75	0.70					
L	0.225	0.325	0.275					
Z	0.20 BSC							
Z 1	0.110 BSC							
All Dimensions in mm								

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.650
Χ	0.400
X1	0.480
X2	0.950
Х3	1.700
Υ	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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